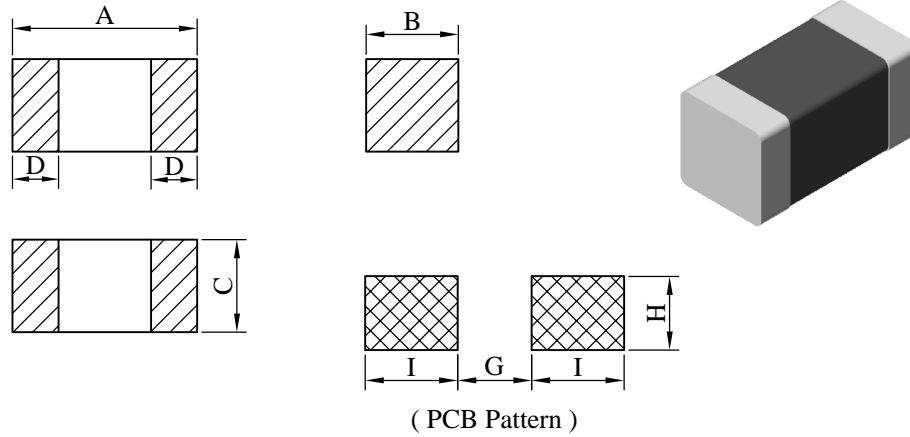


SPECIFICATION FOR APPROVAL

REF. :

| | | | | | |
|------------|----------------------|---------------|------------|------------------|---|
| PROD. NAME | Multilayer Chip Bead | ABC'S DWG NO. | | M□1608□□□□L□-□□□ | |
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I . Configuration and dimensions :



Unit : m/m

| A | B | C | D | G | H | I |
|------------|------------|------------|------------|------|------|------|
| 1.60 ±0.20 | 0.80 ±0.20 | 0.80 ±0.20 | 0.30 ±0.20 | 0.70 | 0.70 | 0.70 |

II . Materials :

- a . Body : Ferrite
- b . Internal conductor : Silver
- c . Terminal electrode : Ag / Ni / Sn
- d . Product weight : 5.4 mg (ref.)
- e . Products comply with RoHS' requirements
- f . Halogen free available.

III . General specification :

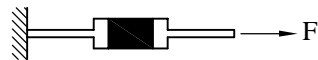
a . Storage Conditions :

Electrical Performance temp : -55°C ---- +125°C

Terminal Solderability & Packages Material temp : -10°C ---- +40°C and RH 70% max.

b . Operating temp. : -55°C ---- +125°C

c . Terminal strength :

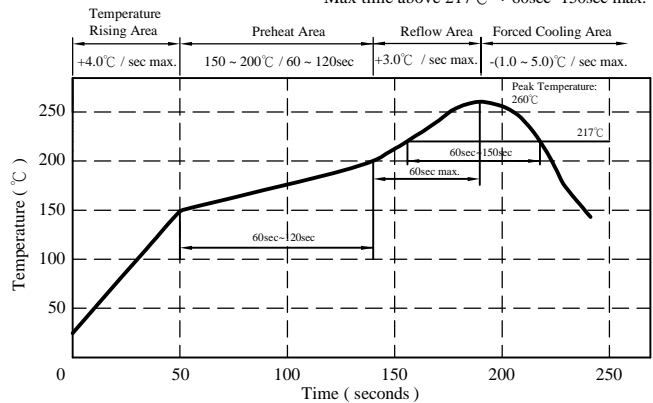


| Type | F (kgf) | Time (sec) |
|--------|-----------|--------------|
| M□1608 | 0.5 | 30±5 |

d . Resistance to soldering heat :

Solder temp. : 260°C
Dip time : 10 sec max.

Peak Temp : 260°C max.
Max. Peak Temp - 5°C : 30sec max.
Max time above 217°C : 60sec~150sec max.



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SPECIFICATION FOR APPROVAL

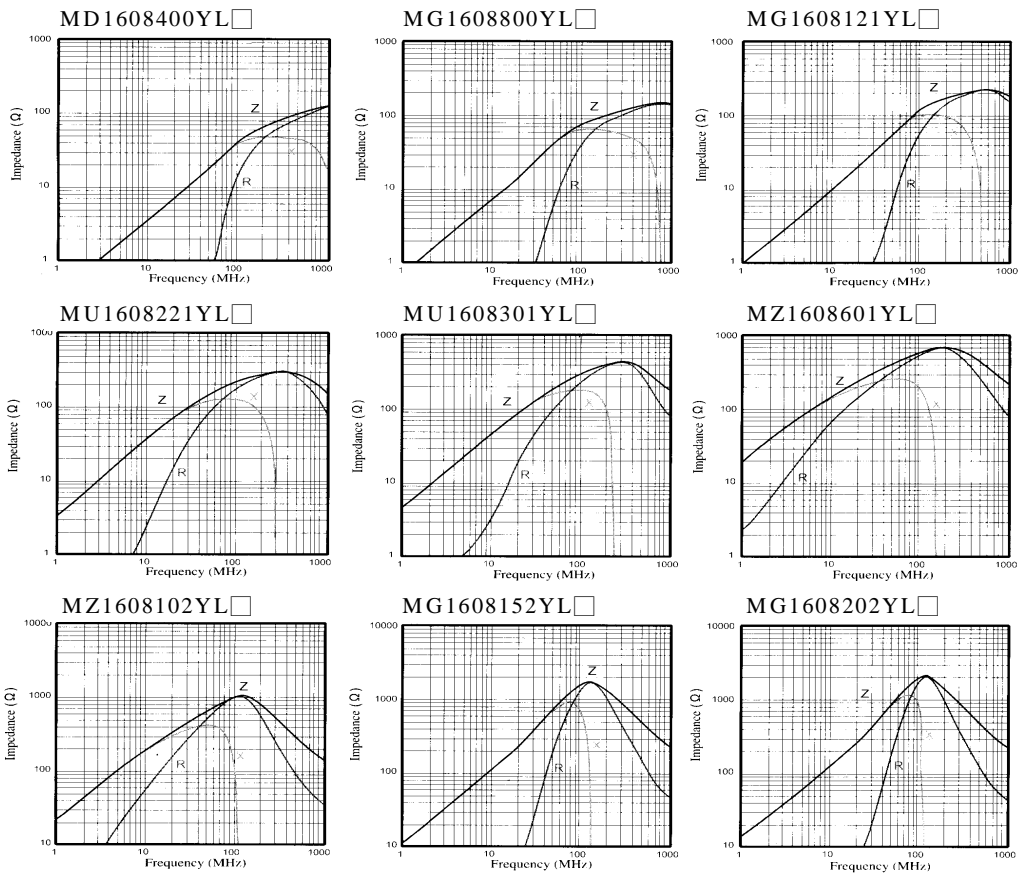
REF. :

| | | | | | |
|---------------|----------------------|---------------|------------------|------|---|
| PROD. NAME | Multilayer Chip Bead | ABC'S DWG NO. | M□1608□□□□L□-□□□ | | |
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IV . Electrical characteristics :

| DWG No. | Impedance (Ω) at 100MHz | RDC (Ω) max. | IDC (mA) max. |
|------------------|--|-----------------------------|---------------------|
| MD1608400YL□-□□□ | 40±25% | 0.30 | 300 |
| MG1608800YL□-□□□ | 80±25% | 0.20 | 300 |
| MG1608121YL□-□□□ | 120±25% | 0.20 | 200 |
| MU1608221YL□-□□□ | 220±25% | 0.20 | 200 |
| MU1608301YL□-□□□ | 300±25% | 0.35 | 200 |
| MZ1608601YL□-□□□ | 600±25% | 0.45 | 200 |
| MZ1608102YL□-□□□ | 1000±25% | 0.60 | 100 |
| MG1608152YL□-□□□ | 1500±25% | 0.70 | 50 |
| MG1608202YL□-□□□ | 2000±25% | 0.80 | 50 |

- 1). □ : Packaging information : □ Code
- 2). "-□□□" : Reference code
- 3). Electrical specifications at 25°C



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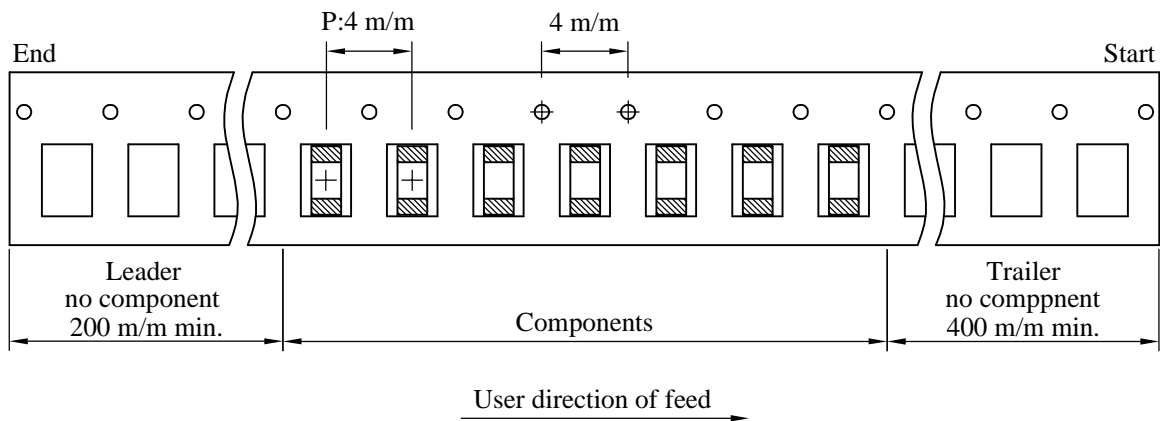
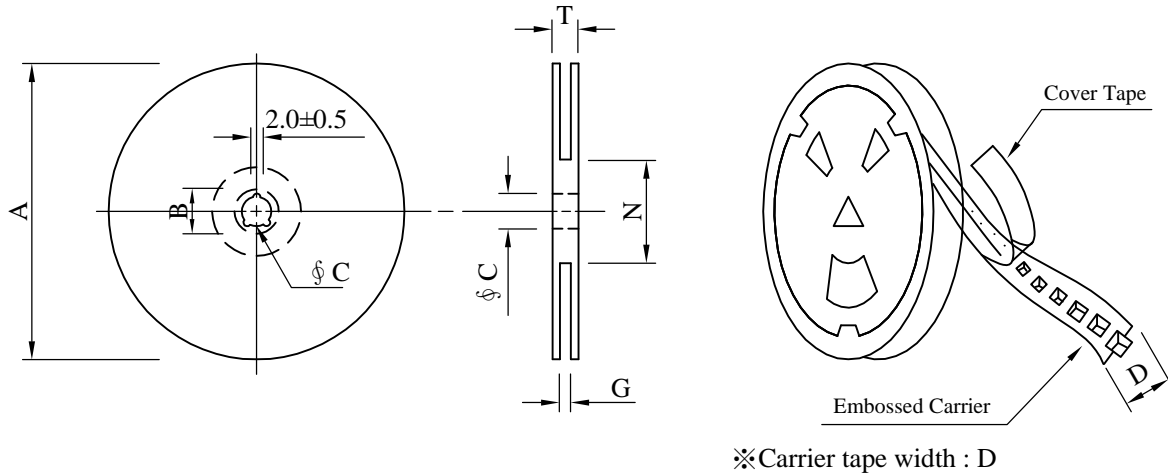
SPECIFICATION FOR APPROVAL

REF. :

| | | | | | |
|------------|----------------------|---------------|------------------|------|---|
| PROD. NAME | Multilayer Chip Bead | ABC'S DWG NO. | M□1608□□□□L□-□□□ | | |
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V . Packaging information :

(1) Configuration



(2) Dimensions

Unit:m/m

| Style | A | B | C | D | G | N | T |
|---------|-----|--------|----|---|------------------|------------------|------|
| 07 - 08 | 178 | 21±0.8 | 13 | 8 | 10 ⁺⁰ | 50 ⁻⁰ | 12.5 |

(3) Q'TY & G.W. Per package

| Code | Inner : Reel | | | Outer : Carton | | |
|------|--------------|-----------|---------|----------------|-----------|--------------|
| | Q'TY (pcs) | G.W. (gw) | Style | Q'TY(kpcs) | G.W. (Kg) | Size (cm) |
| B | 4,000 | 90 | 07 - 08 | 200 | 7.0 | 41 x 39 x 22 |

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SPECIFICATION FOR APPROVAL

REF. :

| | | | | | |
|------------|----------------------|---------------|------------------|------|---|
| PROD. NAME | Multilayer Chip Bead | ABC'S DWG NO. | M□1608□□□□L□-□□□ | | |
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VI . Reliability test :

| Item | Reference documents | Test Condition | Test Specification |
|-------------------------------------|------------------------|---|--|
| 1.High Temperature Exposure | MIL-STD-202 Method 108 | 1.Temperature: 125°C 2.Time:1008 hours. 3.Measurement : After placing for 24 hours min. | 1.Body: No damage 2.Impedance shall not change more than ±30%. |
| 2.Low Temperature Exposure | JESD22-A119 | 1.Temperature: -55°C 2.Time:1008 hours. 3.Measurement : After placing for 24 hours min. | 1.Body: No damage 2.Impedance shall not change more than ±30%. |
| 3.Temperature Cycling | JESD22-A 104 | 1.Temperature: -55°C ~ 125°C 2.Number of cycle:100 cycle 3.Dwell time:30 minutes 4.Measurement : After placing for 24 hours min. | 1.Body: No damage 2.Impedance shall not change more than ±30%. |
| 4.Biased Humidity Test | MIL-STD-202 Method 103 | 1.Temperature:40±5 °C 2.Time:1008 Hours 3.Humidity: 95% RH. 4.Measurement : After placing for 24 hours min. | 1.Body: No damage 2.Impedance shall not change more than ±30%. |
| 5.Vibration Test | MIL-STD-202 Method 204 | 1.Frequency and Amplitued : 10-55-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total. | Appearance: No damage |
| 6.Resistance To Soldering Heat Test | MIL-STD-202 Method 210 | 1.Solder Temp. : 265±3°C 2.Immersion time : 6±1 sec 3.Preheating : 100°C to 150°C, 1 minute. 4.Measurement : After placing for 24 hours min. | 1.Appearance: No damage 2.Impedance shall not change more than ±30%. |
| 7.Solderability Test | J-STD-002 | 1.Preheat : 150°C,60 seconds 2.Solder temperature : 245±5°C 3.Flux 4.Dip time : 4±1 seconds | The terminal shall be at least 90% covered with fresh solder. |
| 8.Terminal Strength Test | IEC 60068-2-21 | 1.Apply push force to samples mounted on PCB. 2.Force: Refer to product specification. 3.Dwell time : >25 seconds. | The terminal electrode and the body shall not be damaged by the forces applied on the right conditions. |
| 9.Board Flex | JIS-C-6429 | 1.Deflection speed : 1 mm/ sec 2.Amount of deflection : 2 mm 3.Span : 90 mm 4.Direction for test : Bottom of PCB 5.Holding time : 60 seconds. | 1.Appearance: No damage 2.The terminal electrode and the body shall not be damaged by the forces applied on the right conditions. |

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